# Embedded Module with Rockchip PX30

Open Standard Module™ - iesy RPX30 OSM-SF

Technical Concept

► Processor: PX30K Quad-Core A35

► CPU Clock-Rate: 1.5 GHz

► RAM: 1 GByte LPDDR3

► Flash-Memory: 8 GByte e-MMC 5.1

► Dimension: 30 mm x 30 mm

► Footprint: OSM Size-S
         Land Grid Array (LGA) with 332 contacts

► Supply: Single Supply 5VDC

► Temperature range:
    › Operating: -20 °C to +85 °C
    › Storage: -40 °C to +85 °C

► Power consumption: 0.3 W (typ.) / 1.8 W (max.)

► Features & Interfaces

    > 1 x LAN 10/100 (RMII)
    > 2 x USB 2.0 Client/Host/OTG
    > 1x MIPI DSI (4 Lanes)
    > 1x MIPI CSI (4 Lanes, incl. I2C)
    > 1x SD-Card
    > 2x SPI, 2x UART, 1x Debug-UART
    > 2x I2C, 1x I2S
    > 18x GPIO
    > 2x ADC (10 bit, SAR), 4x PWM
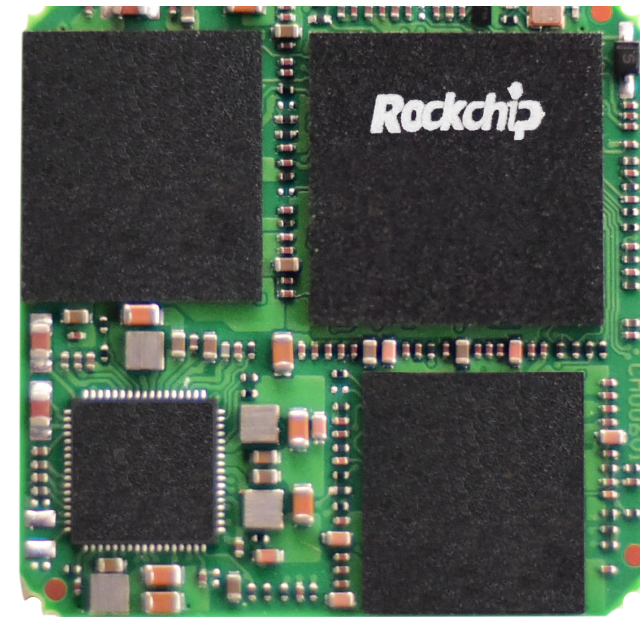
About OSM™

The Open Standard Modules™ specification was adopted by the SGeT e.V. in 2019. The new standard was developed to meet future requirements in terms of **flexibility**, **scalability**, but also **costs**. OSM™ solder-down modules can be **individually adapted** to the respective customer requirements. For this purpose, the individual modules can be made **available to the SMT process** by means of tray & reel packaging and processed automatically. The OSM™ series includes in total four different form factors.

iesy.com/osm